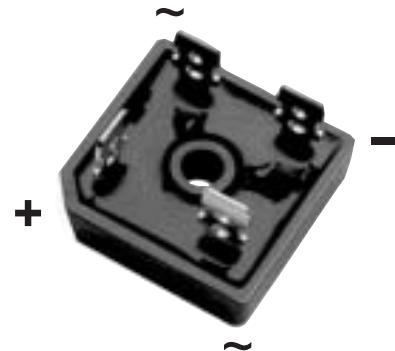


Glass Passivated Single-Phase Bridge Rectifier, 50A

GBPC5006 Thru GBPC5016

FEATURES

- UL recognition file number E320098
- Universal 3-way terminals: snap-on, wire wrap-around, or PCB mounting
- Typical IR less than 1.0 μ A
- High surge current capability
- Low thermal resistance
- Solder dip 260°C, 40s
- Compliant to RoHS
- Glass passivated chips



TYPICAL APPLICATIONS

General purpose use in AC/DC bridge full wave rectification for power supply, home appliances, office equipment, industrial automation applications.

MECHANICAL DATA

Case: GBPC

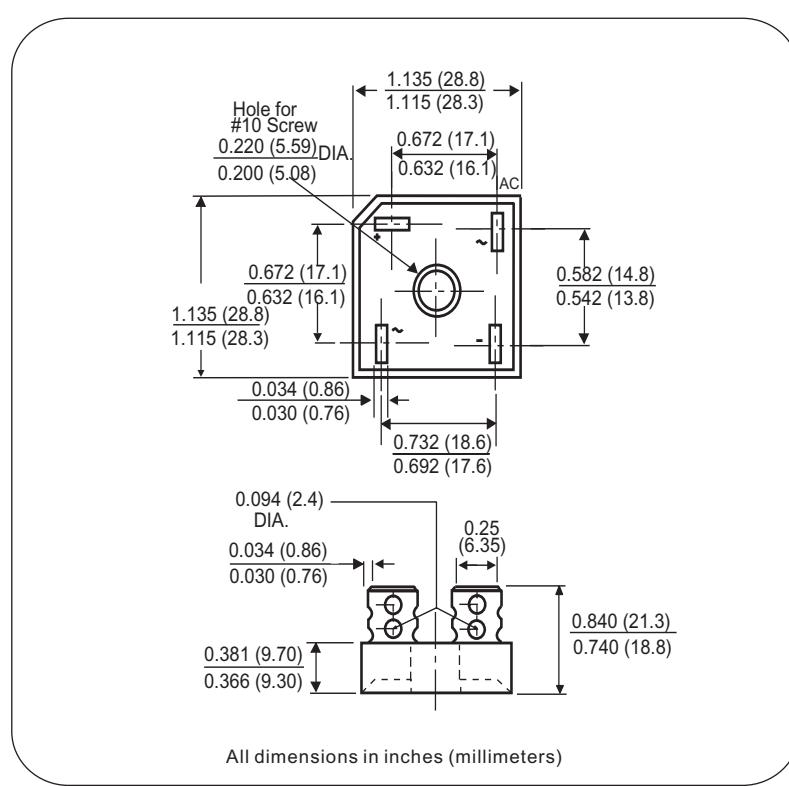
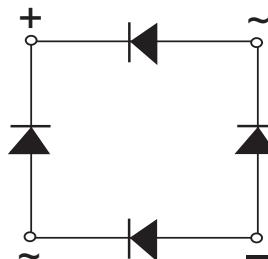
Epoxy meets UL 94 V-O flammability rating

Terminals: Nickel plated on faston lugs or silver plated on wire leads, solderable per J-STD-002 and JESD22-B102.

Polarity: As marked, positive lead by beveled corner

Mounting Torque: 20 inches-lbs. max. (M5 screw)

Weight: 16g (0.56 ozs)



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	50A
V_{RRM}	600V to 1600V
I_{FSM}	450A
I_R	5 μ A
V_F	1.1V
$T_{J\max.}$	150°C

PARAMETER	SYMBOL	GBPC50					UNIT
		06	08	10	12	16	
Maximum repetitive peak reverse voltage	V_{RRM}	600	800	1000	1200	1600	V
Maximum RMS voltage	V_{RMS}	420	560	700	840	1120	V
Maximum DC blocking voltage	V_{DC}	600	800	1000	1200	1600	V
Maximum average forward rectified output current (Fig.1)	$I_{F(AV)}$	50				A	
Peak forward surge current single sine-wave superimposed on rated load	I_{FSM}	450				A	
Rating (non-repetitive, for t greater than 1 ms and less than 8.3 ms) for fusing	I^2t	840				A^2s	
RMS isolation voltage from case to leads	V_{ISO}	2500				V	
Operating junction storage temperature range	$T_{J,T_{STG}}$	-55 to 150				°C	

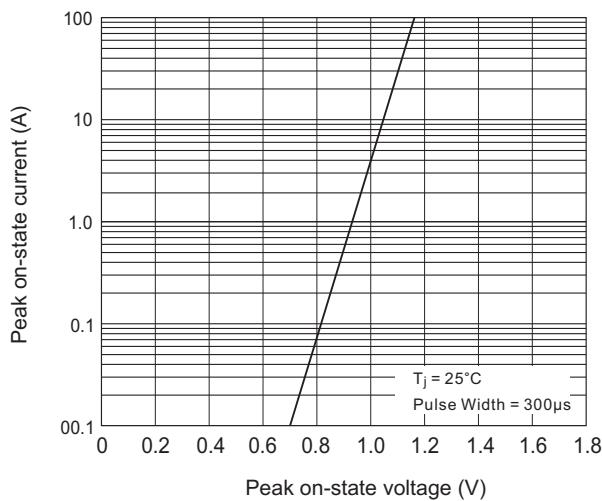
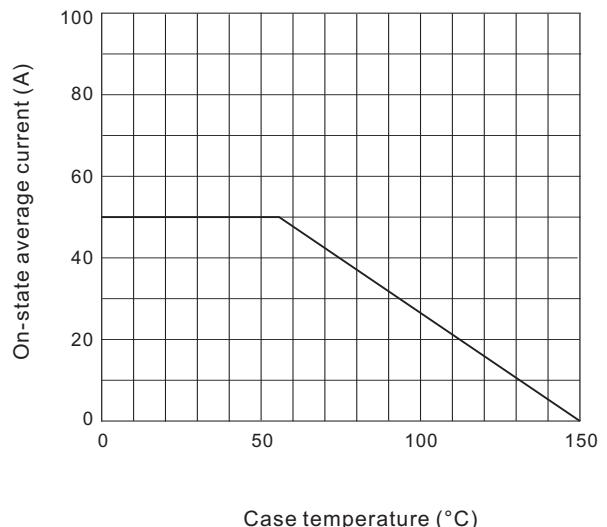
ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise noted)							
PARAMETER	TEST CONDITIONS	SYMBOL	GBPC50				UNIT
			06	08	10	12	
Maximum instantaneous forward drop per diode	$I_F = 25A$	V_F	1.1				V
Maximum reverse DC current at rated DC blocking voltage per diode	$T_A = 25^\circ C$	I_R	5				μA
	$T_A = 150^\circ C$		500				
Typical junction capacitance per diode	4V, 1MHz	C_J	300				pF

THERMAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise noted)							
PARAMETER	SYMBOL	GBPC50					UNIT
		06	08	10	12	16	
Typical thermal resistance	$R_{\theta JC}^{(1)}$	1.4				°C/W	

Notes

(1) With heatsink

(2) Bolt down on heatsink with silicone thermal compound between bridge and mounting surface for maximum heat transfer with M5 screw

Fig.1 On-state current and voltage

Fig.2 Case temperature vs on-state average current

Fig.3 On-state surge current vs cycles
